Panasonic

2SK1103 Silicon N-channel junction FET

For switching circuits Complementary to 2SJ0163

Features

- Low ON resistance
- Low-noise characteristics

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Gate-drain surrender voltage	V _{GDS}	-65	V
Drain current	ID	20	mA
Gate current	I _G	10	mA
Power dissipation	P _D	150	mW
Channel temperature	T _{ch}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



- Pin Name
- 1: Source
- 2: Drain
- 3: Gate

Marking Symbol: 4L

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

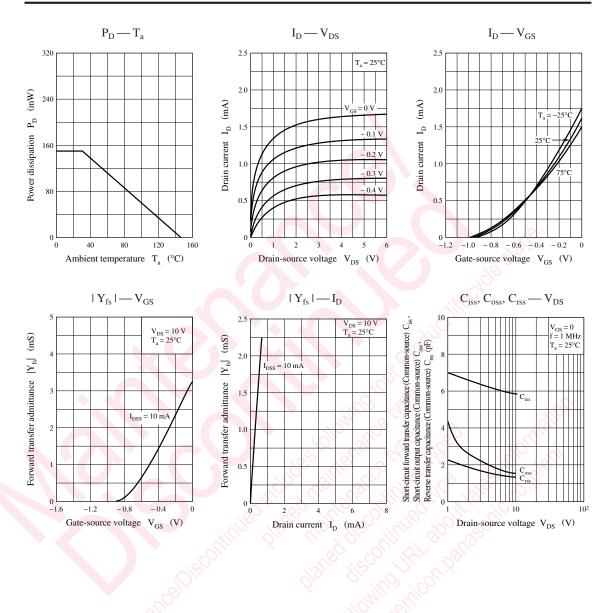
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Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Gate-drain surrender voltage	V _{GDS}	$I_{\rm G} = -10 \ \mu {\rm A}, \ {\rm V}_{\rm DS} = 0$	-65			V
Drain-source current *	I _{DSS}	$V_{DS} = 10 V, V_{GS} = 0$	0.6	5	6.0	mA
Gate-source cutoff current	I _{GSS}	$V_{GS} = -30 \text{ V}, V_{DS} = 0$	CS)		-10	nA
Gate-source cutoff voltage	V _{GSC}	$V_{DS} = 10 \text{ V}, I_D = 10 \mu\text{A}$	$\Omega^{,\chi}$	-1.5	-3.5	V
Forward transfer admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}, f = 1 \text{ kHz}$	1.8	2.5		mS
Drain-source ON resistance	R _{DS(on)}	$V_{DS} = 10 \text{ mV}, V_{GS} = 0$		300		Ω
Short-circuit forward transfer capacitance	C _{iss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		7		pF
(Common source)		inst under				
Reverse transfer capacitance	C _{rss}			1.5		pF
(Common source)		Nor Alter				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.2. Observe precautions for handling. Electrostatic sensitive devices.

3. *: Rank classification

Rank	P	Q	R
I _{DSS} (mA	A) 0.6 to 1.5	5 1.0 to 3.0	2.5 to 6.0

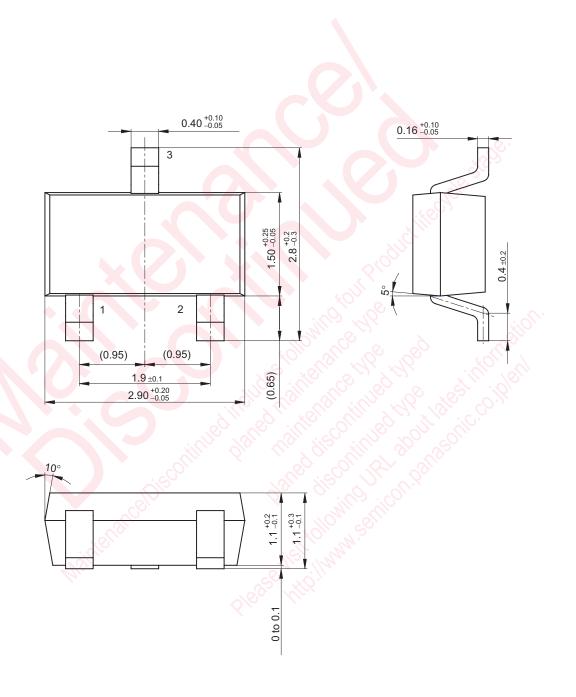
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Mini3-G1

Unit: mm



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